

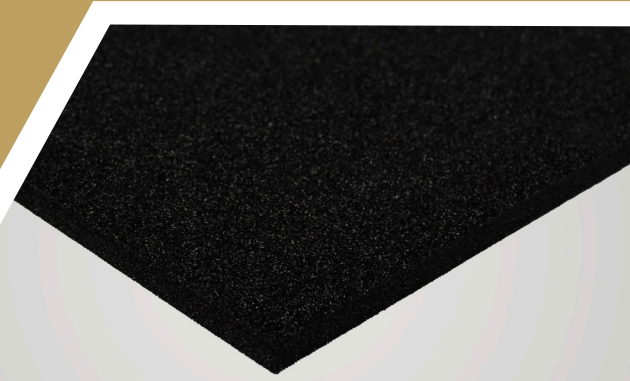


SDFM | LD30

PN: SDFM | LD30

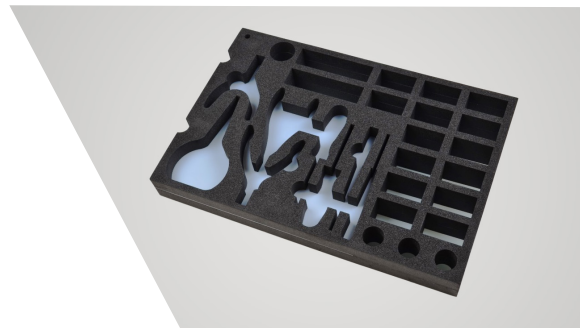
DESCRIPTION: Permanent Dissipative Crosslink PE Foam

APPLICATION: Long-Term Use



MATERIAL INFO

SDFM is a permanently static dissipative crosslink polyethylene foam that has low sloughing. This material can be die cut or waterjet cut to make precise cavities to hold your device secure when ESD and FOD are of high concern.



CHARACTERISTICS

- 10⁴-10⁹ resistance
- Black
- Thermoformable
- Easy to die cut or water jet cut

APPLICATIONS

- Workstation pads
- Die cut dunnage for shielding containers
- Case inserts
- Heavy or lightweight unit cushioning

SPECIFICATIONS

| PROPERTY | VALUE (U.S.) | TEST METHOD |
|---------------------|--|------------------------|
| Color | Black | Visual |
| Volume Resistance | 10 ⁴ -10 ⁹ Ohms/sq | ANSI/ESD STM11.12-2021 |
| Surface Resistance | 10 ⁴ -10 ⁹ Ohms/sq | ANSI/ESD STM11.11-2022 |
| Apparent Density | 1.87 lbs/ft ³ | FTMS 101-C 4046.1 |
| Max Operating Temp* | 203 °F | Internal |

* Recommend maximum operating temperature

All values are for pre-formed materials. Electrical values will vary with each individual design.

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